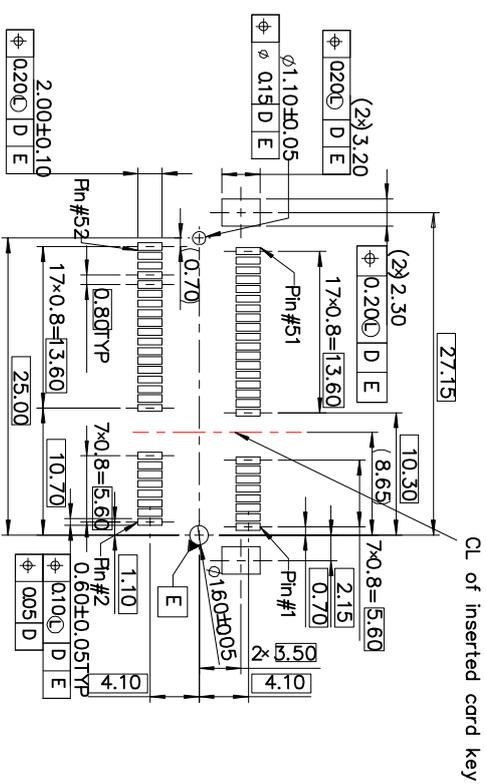
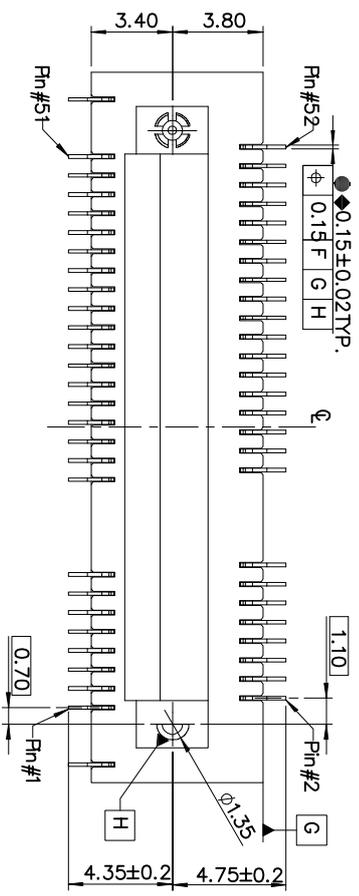
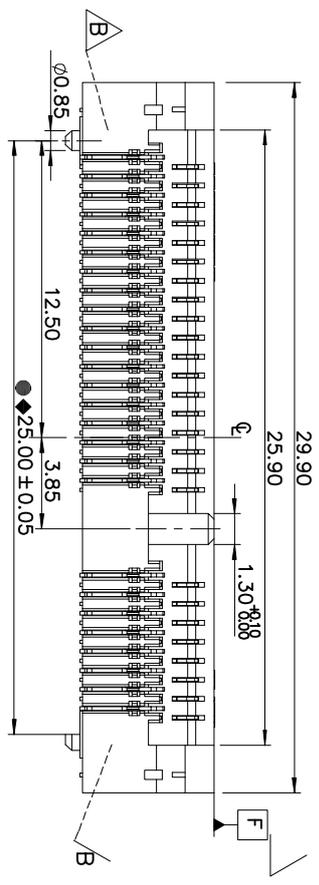
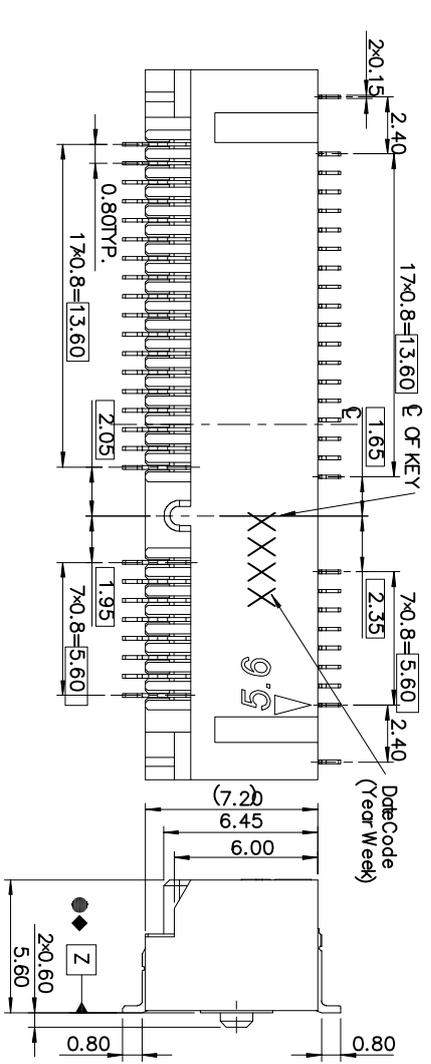


REV.	ECN NO.	MODIFY MATTER	DATE	APPROVED
A		RELEASE TO PRODUCTION	2013/02/05	Mk.e



- NOTE:
- SOLDER TAIL TO BE WITHIN 0.05PW AND 0.2DOWNWARD FROM ZD ATUM PLACE, AND COPLANARITY OF SOLDER TAIL TO BE WITHIN 0.10 MEASUREMENT POINT IS SOLDER TAIL TIP.
  - HSEHSF CONCRRAFT LEVEL 1
  - MATERIAL: HOUSING HIGH-TEMPERATURE PLASTIC, COLOR: BLACK, U 94V-0
  - TERMINAL: COPPER ALLOY
  - 4FINISH: TERMINAL: NICKEL UNDERPLATING ALL OVER BASE MATERIAL CONTACT AREA, GOLD FLASH PLATING OVER UNDERPLATE SOLDER AREA; GOLD FLASH PLATING OVER UNDERPLATE
  - INSPECTION SYMBOL:
    - MANUFACTURER INSPECTION
    - Q.C INSPECTION

TOLERANCES UNLESS OTHERWISE SPECIFIED:		INSPECTION COPY		DRAWING: chenlei		CHECKED: qinlx		APPROVED: qinlx		DATE: 2013/02/05	
X	± 0.38	COPY		2013/02/05		qinlx		qinlx		2013/02/05	
X	± 0.25	COPY		2013/02/05		qinlx		qinlx		2013/02/05	
X	± 0.20	COPY		2013/02/05		qinlx		qinlx		2013/02/05	
X	± 3°	COPY		2013/02/05		qinlx		qinlx		2013/02/05	
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DRAWING: chenlei				CHECKED: qinlx				APPROVED: qinlx			
DATE: 2013/02/05				DATE: 2013/02/05				DATE: 2013/02/05			
PART NO: MINI PCIE 52P H5.6				PART NO: MINI PCIE 52P H5.6				PART NO: MINI PCIE 52P H5.6			
SCALE: N/A				SCALE: N/A				SCALE: N/A			
SHEET: 1/1				SHEET: 1/1				SHEET: 1/1			
REV: A				REV: A				REV: A			

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